# Method for manufacturing a housing for a chip having a micromechanical structure

Abstract

A method for manufacturing a housing for a chip having a micromechanical structure is primarily based on a first basis comprising a photolithograpically structurable layer on at least one partial region of a main face. The same is structured in order to obtain a cover for the micromechanical structure. Further, a chip comprising the micromechanical structure is provided, which is arranged at a main face of the chip between the first contact elements. A second photolithograpically structurable layer is applied to at least one partial region of the main face of the chip and is structured for generating a recess in the same surrounded by a wall in the region of the micromechanical structure and for exposing the first contact elements. After that, the first basis and the chip are merged such that the micromechanical structure and the cover are facing each other and are aligned with each other, so that the recess is closed by the cover. Removing the first basis leads to a chip comprising an on-chip cavity. Afterwards, a second basis and the chip are merged such that the first contact elements are connected to the second basis via a conductive structure. Afterwards, the second basis is removed for exposing the conductive structure. The method is less subject to the cost and size limitations of known housing technologies.